

LMS1487

MS1487 5V Low Power RS-485 / RS-422 Differential Bus Transceiver

5V Low Power RS-485 / RS-422 Differential Bus Transceiver

General Description

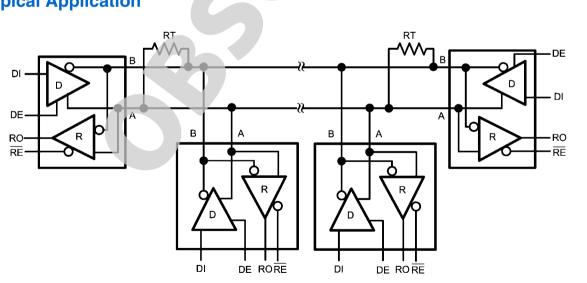
The LMS1487 is a low power differential bus/line transceiver designed for high speed bidirectional data communication on multipoint bus transmission lines. It is designed for balanced transmission lines. It meets ANSI Standards TIA/EIA RS422-B, TIA/EIA RS485-A and ITU recommendation and V.11 and X.27. The LMS1487 combines a TRI-STATE® differential line driver and differential input receiver, both of which operate from a single 5.0V power supply. The driver and receiver have an active high and active low, respectively, that can be externally connected to function as a direction control. The driver and receiver differential inputs are internally connected to form differential input/output (I/O) bus ports that are designed to offer minimum loading to bus whenever the driver is disabled or when $V_{CC} = 0V$. These ports feature wide positive and negative common mode voltage ranges, making the device suitable for multipoint applications in noisy environments. The LMS1487 is available in a 8-Pin SOIC and 8-pin DIP packages. It is a drop-in socket replacement to Maxim's MAX1487

Features

- Meet ANSI standard RS-485-A and RS-422-B
- Data rate 2.5 Mbps
- Single supply voltage operation, 5V
- Wide input and output voltage range
- Thermal shutdown protection
- Short circuit protection
- Low quiescent current 320µA
- Allows up to 128 transceivers on the bus
- Open circuit fail-safe for receiver
- Extended operating temperature range -40°C to 85°C
- Drop-in replacement to MAX1487
- Available in 8-pin SOIC and 8-pin DIP package

Applications

- Low power RS-485 systems
- Network hubs, bridges, and routers
- Point of sales equipment (ATM, barcode scanners,...)
- Local area networks (LAN)
- Integrated service digital network (ISDN)
- Industrial programmable logic controllers
- High speed parallel and serial applications
- Multipoint applications with noisy environment



20053001

A Typical multipoint application is shown in the above figure. Terminating resistors, RT, are typically required but only located at the two ends of the cable. Pull up and pull down resistors maybe required at the end of the bus to provide fail-safe biasing. The biasing resistors provide a bias to the cable when all drivers are in TRI-STATE, See National Application Note, AN-847 for further information.

TRI-STATE® is a registered trademark of National Semiconductor Corporation.

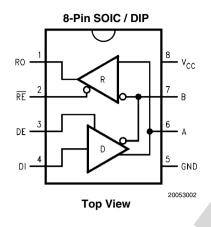
© 2011 National Semiconductor Corporation 200530

www.national.com

Typical Application

LMS1487

Connection Diagram



Truth Table

DRIVER SECTION						
RE	DE	DI A	В			
Х	Н	Н	L			
Х	Н	L	Н			
X	L	X Z	Z			
RECEIVER SECTION						
RE	DE	A-B	RO			
L	L	≥ +0.2V	Н			
L	L	≤ -0.2V	L			
Н	Х	X	Z			
L	L	OPEN *	Н			

Note: * = Non Terminated, Open Input only

X = Irrelevant

- Z = TRI-STATE
- H = High level
- L = Low level

Pin Descriptions

Pin #	I/O	Name	Function			
1	0	RO	Receiver Output: If A > B by 200 mV, RO will be high; If A < B by 200mV, RO will be low. RO will be			
			high also if the inputs (A and B) are open (non-terminated			
2		RE	Receiver Output Enable: RO is enabled when \overline{RE} is low; RO is in TRI-STATE when \overline{RE} is high			
3	I	DE	Driver Output Enable: The driver outputs (A and B) are enabled when DE is high; they are in TRI- STATE when DE is low. Pins A and B also function as the receiver input pins (see below)			
4	I	DI	Driver Input: A low on DI forces A low and B high while a high on DI forces A high and B low when the driver is enabled			
5	N/A	GND	Ground			
6	I/O	A	Non-inverting Driver Output and Receiver Input pin. Driver Output levels conform to RS-485 signaling levels			
7	I/O	В	Inverting Driver Output and Receiver Input pin. Driver Output levels conform to RS-485 signaling levels			
8	N/A	V _{CC}	Power Supply: $4.75V \le V_{CC} \le 5.25V$			

Package	Part Number	Package Marking	Transport Media	NSC Drawing	
	LMS1487CM		95 Units/Rail		
	LMS1487CMX	LMS1487CM	2.5k Units Tape and Reel	1400.4	
8-Pin SOIC	LMS1487IM		95 Units/Rail	M08A	
	LMS1487IMX	LMS1487IM	2.5k Units Tape and Reel		
	LMS1487CNA	LMS1487CNA	40 Units/Rail	NOOF	
8-Pin DIP	LMS1487INA	LMS1487INA	40 Units/Rail	N08E	

Γ

Absolute Maximum Ratings (Note 1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/ Distributors for availability and specifications.

Supply Voltage, V _{CC} (Note 2)	7V
Input Voltage, V _{IN} (DI, DE, or RE)	–0.3V to V_{CC} + 0.3V
Voltage Range at Any Bus Terminal	
(AB)	–7V to 12V
Receiver Outputs	–0.3V to V _{CC} + 0.3V
Package Thermal Impedance, θ_{JA}	
SOIC	125°C/W
DIP	88°C/W
Junction Temperature (Note 3)	150°C
Operating Free-Air Temperature	
Range, T _A	
Commercial	0°C to 70°C
Industrial	–40°C to 85°C
Storage Temperature Range	–65°C to 150°C
Soldering Information	
Infrared or Convection (20 sec.)	235°C

Lead Temperature	
ESD Rating (Note 4)	

260°C 7kV

Operating Ratings

	Min	Nom	Max	
Supply Voltage, V _{CC}	4.75	5.0	5.25	V
Voltage at any Bus Terminal (Separately or Common Mode)	-7		12	V
V _{IN} or V _{IC}				
High-Level Input Voltage, V _{IH} (Note 5)	2			V
Low-Level Input Voltage, V _{IL}			0.8	V
(Note 5)				
Differential Input Voltage, V _{ID} (Note 6)			±12	V
High-Level Output				
Driver, I _{OH}			-15 0	mA
Receiver, I _{OH}			-42	mA
Low-Level Output				
Driver, I _{OL}			80	mA
Receiver, I _{OL}			26	mA

Electrical Characteristics

Over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

Symbol	Parameter	Conditions	Min	Тур	Max	Units
Driver Sec	tion			•	•	
V _{OD1}	Differential Output Voltage	$R = \infty$ (Figure 1)			5.25	V
V _{OD2}	Differential Output Voltage	R = 50Ω (Figure 1) ,RS-422	2.0			V
		R = 27Ω (Figure 1) ,RS-485	1.5		5.0	
ΔV _{OD}	Change in Magnitude of Driver Differential Output Voltage for Complementary Output States	$R = 27\Omega \text{ or } 50\Omega \text{ (Figure 1)}, \text{ (Note 7)}$			0.2	V
V _{oc}	Common-Mode Output Voltage	R = 27Ω or 50Ω (Figure 1)			3.0	V
ΔV _{OC}	Change in Magnitude of Driver Common-Mode Output Voltage for Complementary Output States	$R = 27\Omega$ or 50Ω (Figure 1), (Note 7)			0.2	V
V _{IH}	CMOS Inout Logic Threshold High	DE, DI, RE	2.0			V
V _{IL}	CMOS Input Logic Threshold Low	DE, DI, RE			0.8	v
I _{IN1}	Logic Input Current	DE, DI, RE			±2	μA
Receiver S	ection			•	•	•
I _{IN2}	Input Current (A, B)	DE = 0V, V _{CC} = 0V or 5.25V V _{IN} = 12V			0.25	mA
		$V_{IN} = -7V$			-0.2	
V _{TH}	Differential Input Threshold Voltage	$-7V \le V_{CM} \le + 12V$	-0.2		+0.2	v
ΔV _{TH}	Input Hysteresis Voltage (V _{TH+} – V _{TH-})	V _{CM} = 0		95		mV
V _{OH}	CMOS High-level Output Voltage	I _{OH} = -4mA, V _{ID} = 200mV	3.5			V
V _{OL}	CMOS Low-level	I _{OL} = 4mA, V _{ID} = -200mV			0.40	V

Symbol	Parameter	Conditions	Min	Тур	Max	Units
OZR	Tristate Output Leakage Current	$0.4V \le V_0 \le + 2.4V$			±1	μA
R _{IN}	Input Resistance	$-7V \le V_{CM} \le +12V$	48			kΩ
Power Su	oply Current					
сс	Supply Current	$DE = V_{CC}$, $\overline{RE} = GND$ or V_{CC}		320	500	μA
		$DE = 0V, \overline{RE} = GND \text{ or } V_{CC}$		315	400	1
OSD1	Driver Short-circuit Output Current	$V_{O} = high, -7V \le V_{CM} \le + 12V$ (Note 8)	35		250	mA
OSD2	Driver Short-circuit Output Current	$V_{O} = low, -7V \leq V_{CM} \leq +12V$ (Note 8)	35		250	mA
OSR	Receiver Short-circuit Output Current	$0 \vee \leq V_{O} \leq V_{CC}$	7		95	mA
Switching	Characteristics			•		•
Driver						
Г _{РLН} , Г _{РНL}	Propagation Delay Input to Output	$R_L = 54\Omega, C_L = 100pF$ (Figure 3, Figure 7)	10	35	60	nS
Т _{SKEW}	Driver Output Skew	$R_{L} = 54\Omega, C_{L} = 100 \text{ pF}$ (Figure 3, Figure 7)		5	10	nS
T _R , T _F	Driver Rise and Fall Time	$R_L = 54\Omega, C_L = 100 \text{ pF}$ (Figure 3, Figure 7)	3	8	40	nS
T _{ZH} , T _{ZL}	Driver Enable to Ouput Valid Time	$C_L = 100 \text{ pF}, R_L = 500\Omega$ (Figure 4, Figure 8)		25	70	nS
T _{HZ} , T _{LZ}	Driver Output Disable Time	$C_L = 15 \text{ pF}, R_L = 500\Omega \text{ (Figure 4, Figure 8)}$		30	70	nS
Receiver				•		•
Г _{РLН} , Г _{РНL}	Propagation Delay Input to Output	$R_L = 54\Omega, C_L = 100 \text{ pF}$ (Figure 5, Figure 7)	20	50	200	nS
Г _{SKEW}	Receiver Output Skew	$R_{L} = 54\Omega, C_{L} = 100 \text{ pF}$ (Figure 5, Figure 7)		5		nS
Γ _{ZH} , Γ _{ZL}	Receiver Enable Time	$C_L = 15 \text{ pF}, R_L = 1 \text{ k}\Omega$ (Figure 6, Figure 10)		20	50	nS
	Receiver Disable Time			20	50	nS
мах	Maximum Data Rate		2.5			Mbps

Note 1: Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is intended to be functional, but specific performance is not guaranteed. For guaranteed specifications and the test conditions, see the Electrical Characteristics Note 2: All voltage values, except differential I/O bus voltage, are with respect to network ground terminal.

Note 3: The maximum power dissipation is a function of $T_{J(MAX)}$, θ_{JA} , and T_A . The maximum allowable power dissipation at any ambient temperature is $P_D = (T_J_{(MAX)}, T_A)/\theta_{JA}$. All numbers apply for packages soldered directly into a PC board.

Note 4: ESD rating based upon human body model, 100pF discharged through $1.5k\Omega$.

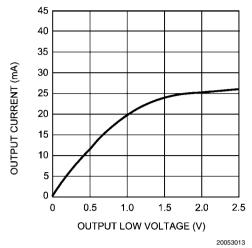
Note 5: Voltage limits apply to DI, DE, \overline{RE} pins.

Note 6: Differential input/output bus voltage is measured at the non-inverting terminal A with respect to the inverting terminal B.

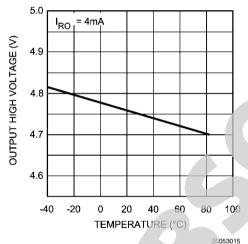
Note 7: $|\Delta V_{OD}|$ and $|\Delta V_{OC}|$ are changes in magnitude of V_{OD} and V_{OC} , respectively when the input changes from high to low levels. Note 8: Peak current LMS1487

Typical Performance Characteristics

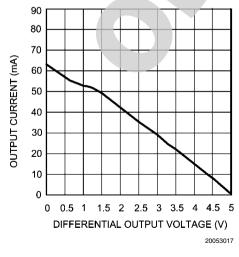
Output Current vs. Receiver Output Low Voltage



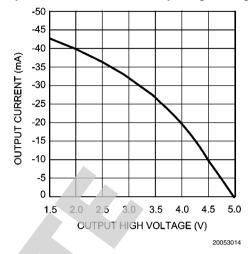
Receiver Output High Voltage vs. Temperature



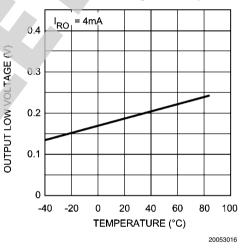
Driver Output Current vs. Differential Output Voltage



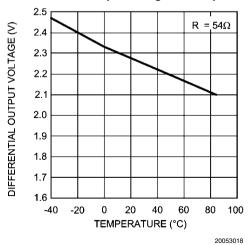
Output Current vs. Receiver Output High Voltage



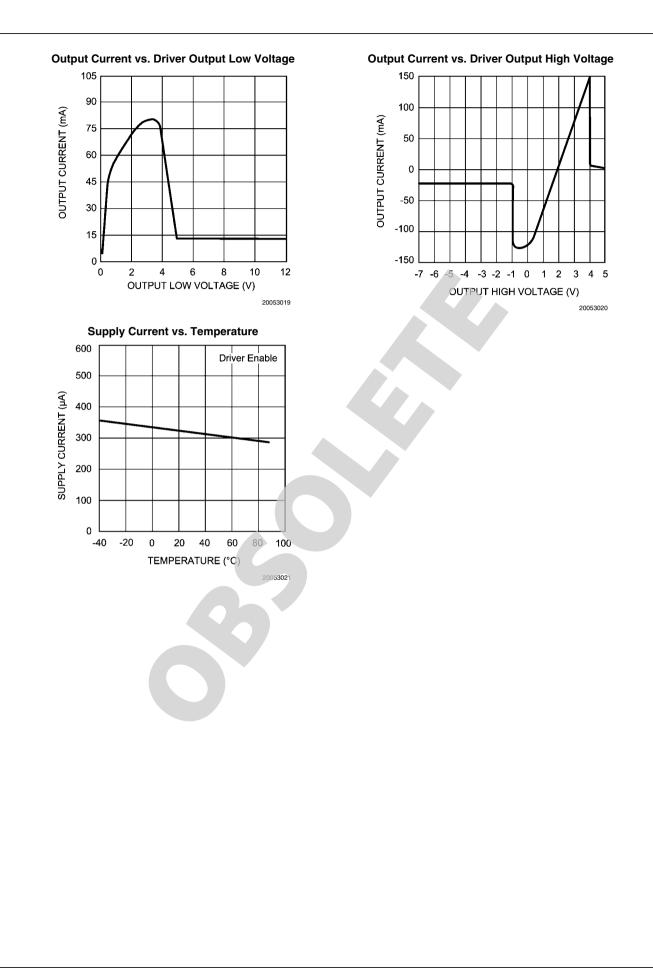
Receiver Output Low-Voltage vs. Temperature



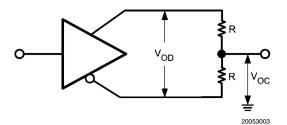
Driver Differential Output Voltage vs. Temperature







Parameter Measuring Information





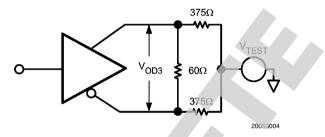
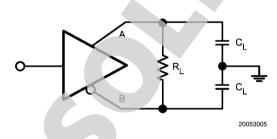


FIGURE 2. Test Circuit for V_{OD3}





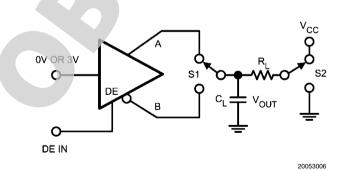


FIGURE 4. Test Circuit for Driver Enable / Disable

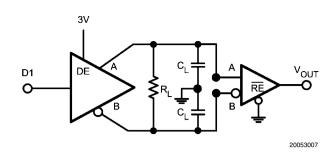
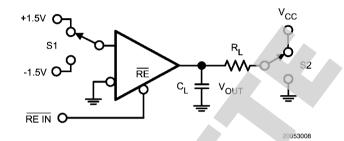


FIGURE 5. Test Circuit for Receiver Propagation Delay





Switching Characteristics

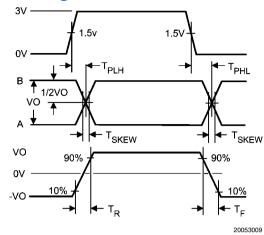


FIGURE 7. Driver Propagation Delay, Rise / Fall Time

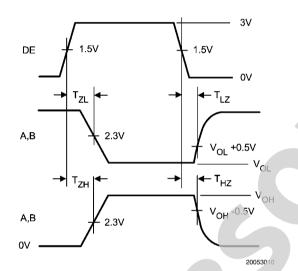
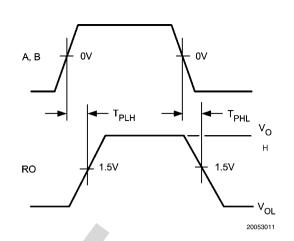


FIGURE 8. Driver Enable / Disable Time





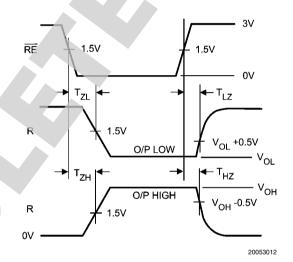


FIGURE 10. Receiver Enable / Disable Time

Application Information

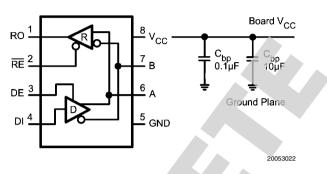
POWER LINE NOISE FILTERING

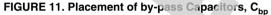
A factor to consider in designing power and ground is noise filtering. A noise filtering circuit is designed to prevent noise generated by the integrated circuit (IC) as well as noise entering the IC from other devices. A common filtering method is to place by-pass capacitors (C_{bp}) between the power and ground lines.

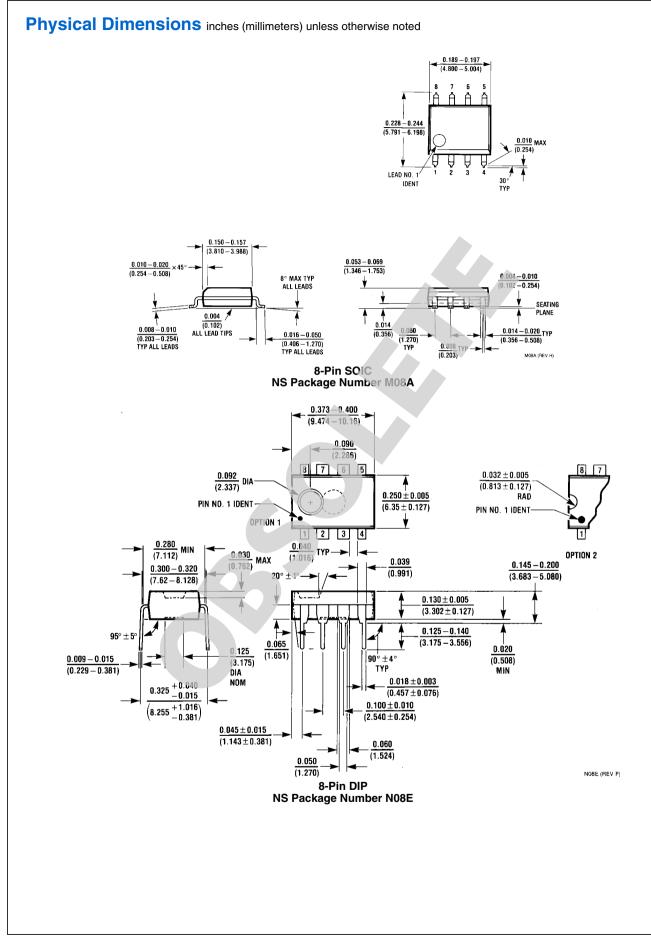
Placing a by-pass capacitor (C_{bp}) with the correct value at the proper location solves many power supply noise problems. Choosing the correct capacitor value is based upon the desired noise filtering range. Since capacitors are not ideal, they

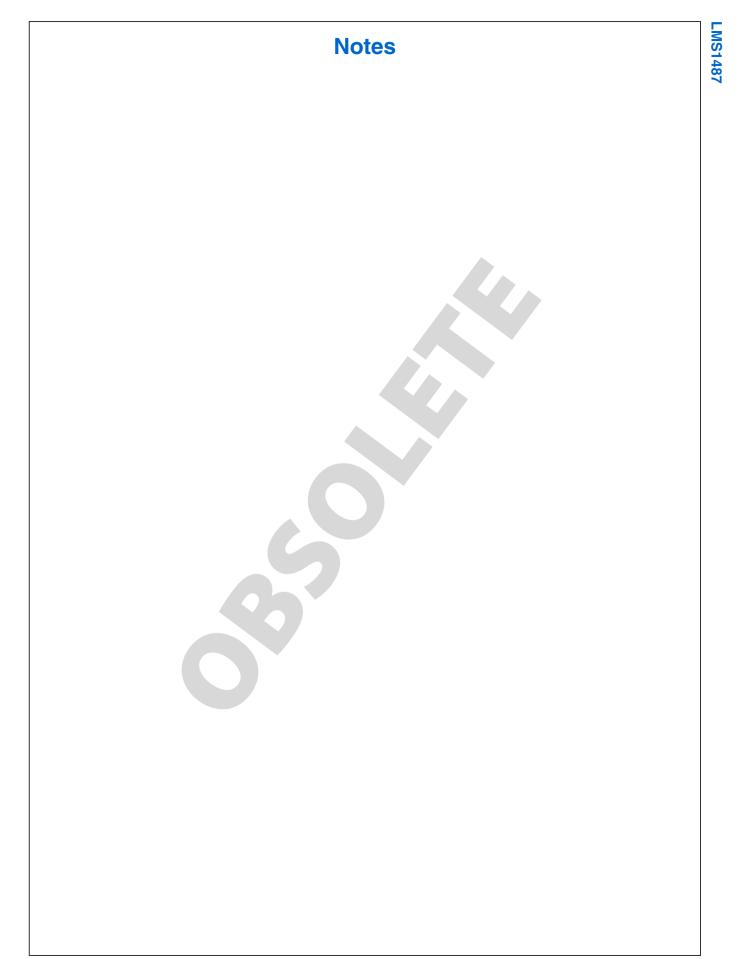
may act more like inductors or resistors over a specific frequency range. Thus, many times two by-pass capacitors may be used to filter a wider bandwidth of noise. It is highly recommended to place a larger capacitor, such as 10 μ F, between the power supply pin and ground to filter out low frequencies and a 0.1 μ F to filter out high frequencies.

By-pass capacitors must be mounted as close as possible to the IC to be effective. Longs leads produce higher impedance at higher frequencies due to stray inductance. Thus, this will reduce the by-pass capacitor's effectiveness. Surface mounted chip capacitors are the best solution because they have lower inductance.









Notes

For more National Semiconductor product information and proven design tools, visit the following Web sites at: www.national.com

Pr	oducts	Design Support		
Amplifiers	www.national.com/amplifiers	WEBENCH® Tools	www.national.com/webench	
Audio	www.national.com/audio	App Notes www.national.com/appn		
Clock and Timing	www.national.com/timing	Reference Designs	www.national.com/refdesigns	
Data Converters	www.national.com/adc	Samples	www.national.com/samples	
Interface	www.national.com/interface	Eval Boards	www.national.com/evalboards	
LVDS	www.national.com/lvds	Packaging	www.national.com/packaging	
Power Management	www.national.com/power	Green Compliance	www.national.com/quality/green	
Switching Regulators	www.national.com/switchers	Distributors	www.national.com/contacts	
LDOs	www.national.com/ldo	Quality and Reliability	www.national.com/quality	
LED Lighting	www.national.com/led	Feedback/Support	www.national.com/feedback	
Voltage References	www.national.com/vref	Design Made Easy	www.national.com/easy	
PowerWise® Solutions	www.national.com/powerwise	Applications & Markets	www.national.com/solutions	
Serial Digital Interface (SDI)	www.national.com/sdi	Mil/Aero	www.national.com/milaero	
Temperature Sensors	www.national.com/tempsensors	SolarMagic™	www.national.com/solarmagic	
PLL/VCO	www.national.com/wireless	PowerWise® Design University	www.national.com/training	

THE CONTENTS OF THIS DOCUMENT ARE PROVIDED IN CONNECTION WITH NATIONAL SEMICONDUCTOR CORPORATION ("NATIONAL") PRODUCTS. NATIONAL MAKES NO REPRESENTATIONS OR WARRANTIES WITH RESPECT TO THE ACCURACY OR COMPLETENESS OF THE CONTENTS OF THIS PUBLICATION AND RESERVES THE RIGHT TO MAKE CHANGES TO SPECIFICATIONS AND PRODUCT DESCRIPTIONS AT ANY TIME WITHOUT NOTICE. NO LICENSE, WHETHER EXPRESS, IMPLIED, ARISING BY ESTOPPEL OR OTHERWISE, TO ANY INTELLECTUAL PROPERTY RIGHTS IS GRANTED BY THIS DOCUMENT.

TESTING AND OTHER QUALITY CONTROLS ARE USED TO THE EXTENT NATIONAL DEEMS NECESSARY TO SUPPORT NATIONAL'S PRODUCT WARRANTY. EXCEPT WHERE MANDATED BY GOVERNMENT REQUIREMENTS, TESTING OF ALL PARAMETERS OF EACH PRODUCT IS NOT NECESSARILY PERFORMED. NATIONAL ASSUMES NO LIABILITY FOR APPLICATIONS ASSISTANCE OR BUYER PRODUCT DESIGN. BUYERS ARE RESPONSIBLE FOR THEIR PRODUCTS AND APPLICATIONS USING NATIONAL COMPONENTS, PRIOR TO USING OR DISTRIBUTING ANY PRODUCTS THAT INCLUDE NATIONAL COMPONENTS, BUYERS SHOULD PROVIDE ADEQUATE DESIGN, TESTING AND OPERATING SAFEGUARDS.

EXCEPT AS PROVIDED IN NATIONAL'S TERMS AND CONDITIONS OF SALE FOR SUCH PRODUCTS. NATIONAL ASSUMES NO LIABILITY WHATSOEVER, AND NATIONAL DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY RELATING TO THE SALE AND/OR USE OF NATIONAL PRODUCTS INCLUDING LIABILITY OR WARRANTIES RELATING TO FITNESS FOR A PARTICULAR PURPOSE, MERCHANTABILITY, OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT.

LIFE SUPPORT POLICY

NATIONAL'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS PRIOR WRITTEN APPROVAL OF THE CHIEF EXECUTIVE OFFICER AND GENERAL COUNSEL OF NATIONAL SEMICONDUCTOR CORPORATION. As used herein:

Life support devices or systems are devices which (a) are intended for surgical implant into the body, or (b) support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in a significant injury to the user. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system or to affect its safety or effectiveness.

National Semiconductor and the National Semiconductor logo are registered trademarks of National Semiconductor Corporation. All other brand or product names may be trademarks or registered trademarks of their respective holders.

Copyright© 2011 National Semiconductor Corporation

For the most current product information visit us at www.national.com



National Semiconductor Americas Technical Support Center Email: support@nsc.com ww.national.com Tel: 1-800-272-9959

National Semiconductor Europe **Technical Support Center** Email: europe.support@nsc.com

National Semiconductor Asia Pacific Technical Support Center Email: ap.support@nsc.com

National Semiconductor Japan **Technical Support Center** Email: ipn.feedback@nsc.com